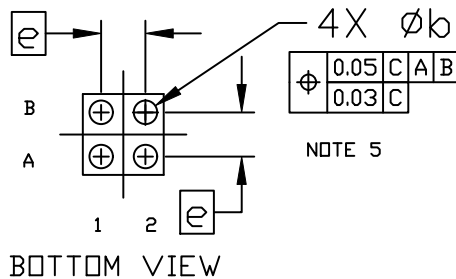
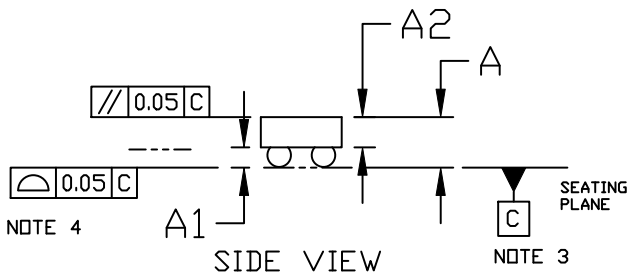
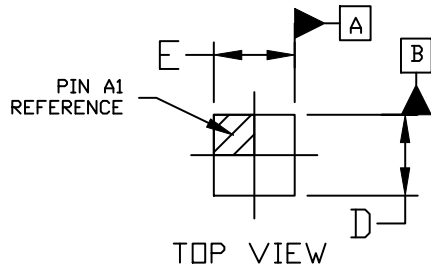



SCALE 4:1

WLCSP4, 0.64x0.64
CASE 567KA
ISSUE B

DATE 24 MAR 2020



GENERIC MARKING DIAGRAM*



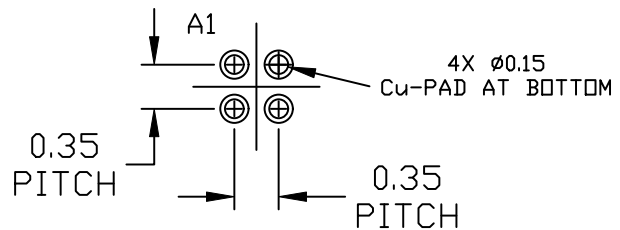
X = Specific Device Code
M = Date Code

This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "", may or may not be present. Some products may not follow the Generic Marking.

NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2009.
2. CONTROLLING DIMENSION: MILLIMETERS
3. DATUM C, THE SEATING PLANE, IS DEFINED BY THE SPHERICAL CROWNS OF THE CONTACT BALLS.
4. COPLANARITY APPLIES TO THE SPHERICAL CROWNS OF THE CONTACT BALLS.
5. DIMENSION b IS MEASURED AT THE MAXIMUM CONTACT BALL DIAMETER PARALLEL TO DATUM C.

DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
A	0.355	0.405	0.455
A1	0.13	0.15	0.17
A2	0.255 REF		
b	0.167	0.187	0.207
D	0.610	0.640	0.670
E	0.610	0.640	0.670
e	0.35 BSC		



* For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERM/D.

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DESCRIPTION:	WLCSP4, 0.64X0.64	PAGE 1 OF 1

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